



Jack	Description	Factory Setting
J1	For bq25892 input current setting: Low adaptor port, High: USB input	bq25892: Not installed, bq25892: short PSEL to LOW
J2	D-PC pin selection	bq25892: short to D-, bq25892: short to PG
J3	STAT1, PG, CE, INT, OTG pins internal pull-up source (SYS)	Short to SYS
J4	D-PC pin selection	bq25892: Not installed, bq25892: installed
J5	Input current limit setting (short D+ and D-)	bq25892: installed, bq25892: Not installed
J6	USB current limit selection pin during back mode and PSEL is high/ Enable pin during boost mode	Not installed
J7	ICE pin setting: pull low to enable charge	Not installed
J8	TS pin to GND	Not installed
J9	TS resistor divider pull-up source (REGN1) connection	Installed
J10	Internal 10k to GND to TS pin	Not installed
J11	ICE pin setting: pull low to enable charge	Not installed
J12	USB current limit selection pin during back mode and PSEL is high/ Enable pin during boost mode	Not installed
J13	Short SCL1 and SCL2, install when two charger have different addresses	Installed
J14	Short SDA1 and SDA2, install when two charger have different addresses	Installed
J15	Pullup source for I2C bus	Installed
J16	Not installed if requires CHG2 at minimum ILM	Installed

Revision	Notes

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H1
SJ-5303 (CLEAR)

H2
SJ-5303 (CLEAR)

H3
SJ-5303 (CLEAR)

H4
SJ-5303 (CLEAR)

DNP
FIL1

DNP
FIL2

DNP
FIL3

PCB Number: PWR692
PCB Rev: E2

PCB LOGO
Texas Instruments

PCB LOGO
FCC disclaimer

PCB LOGO
Pb-Free Symbol

PCB LOGO
ESD Susceptible

LBL1
PCB Label
Size: 0.65" x 0.20"

Variant	Label Text
890 + 892	Dual bq2599xEVM-692-890 + 892
Dual 89x	Dual bq2599xEVM-692-2 X 89x
Dual 19x	Dual bq2419xEVM-692

SH-JP1 SH-JP2 SH-JP3 SH-JP4 SH-JP5 SH-JP6 SH-JP7 SH-JP8 SH-JP9 SH-JP10 SH-JP11 SH-JP12 SH-JP13 SH-JP14 SH-JP15 SH-JP16

Z21
Label Assembly Note
This Assembly Note is for PCB labels only

Z22
Assembly Note
These assemblies are ESD sensitive. ESD precautions shall be observed.

Z23
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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